



Material Content Data Sheet



Sales Product Name		TLE7257SJ		Issued		19. July 2018		
MA#		MA001224096						
Package		PG-DSO-8-44		Weight*		82.63 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.828	1.00	1.00	10020	10020
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		109	
	non noble metal	zinc	7440-66-6	0.036	0.04		434	
	non noble metal	iron	7439-89-6	0.717	0.87		8680	
wire	non noble metal	copper	7440-50-8	29.121	35.24	36.16	352434	361657
	non noble metal	copper	7440-50-8	0.055	0.07	0.07	662	662
	plastics	epoxy resin	-	4.606	5.57		55745	
encapsulation	inorganic material	silicondioxide	60676-86-0	45.360	54.91		548961	
	organic material	carbon black	1333-86-4	0.100	0.12	60.60	1212	605918
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9849	9849
plating	noble metal	silver	7440-22-4	0.650	0.79	0.79	7870	7870
glue	plastics	acrylic resin	-	0.073	0.09		885	
	noble metal	silver	7440-22-4	0.259	0.31	0.40	3139	4024
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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